

AMENDMENTS TO THE CLAIMS

The listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) A resistor foil for use in forming an embedded resistor in a printed circuit board, comprised of:

a copper layer having a first side and a second side;

an ~~intermediate oxide~~ layer having a thickness of between 5 Å and 70 Å on said first side of said copper layer;

a first layer of a first resistor metal having a thickness of between 50 Å and 2 µm formed directly on said ~~intermediate oxide~~ layer, said first resistor metal selected from the group consisting of aluminum, zinc, nickel, nickel/chromium, nickel/chromium/aluminum/silicon alloy, titanium, vanadium, chromium, tantalum, iron, manganese and alloys, oxides, nitrides and silicides thereof; and

a second layer of a second resistor metal having a thickness of between 50 Å and 2 µm formed directly on said first layer of said first resistor metal, said second resistor metal selected from the group consisting of aluminum, zinc, nickel, nickel/chromium, nickel/chromium/aluminum/silicon alloy, titanium, vanadium, chromium, tantalum, iron, manganese and alloys, oxides, nitrides and silicides thereof, wherein said first resistor metal ~~having~~ has a resistance different from said second resistor metal.

2. (canceled).

3. (canceled).

4. (currently amended) A resistor foil as defined in ~~claim 3~~claim 1, wherein said first resistor metal is different from said second resistor metal.

5. (original) A resistor foil as defined in claim 4, wherein said first resistor metal is nickel/chromium/aluminum/silicon alloy.

6. (original) A resistor foil as defined in claim 5, wherein said second resistor metal is tantalum oxide.

7. (canceled).

8. (currently amended) A resistor foil as defined in claim 1, wherein said ~~intermediate oxide layer is comprised of at least one stabilizer layer comprised of one an~~ oxide of a metal selected from the group consisting of copper, zinc, nickel, palladium, titanium, tantalum, aluminum, iron, vanadium, chromium, chromium-based alloys and nickel-based alloys, and combinations thereof.

9. (canceled).

10. (canceled).

11. (canceled).

12. (canceled).

13. (canceled).

14. (canceled).

15. (new) A resistor foil for use in forming an embedded resistor in a printed circuit board, comprised of:

a copper layer having a first side and a second side;

an oxide layer having a thickness of between 5 Å and 70 Å on said first side of said copper layer, wherein said oxide layer is comprised of an oxide of a metal selected from the group consisting of copper, zinc, nickel, palladium, titanium, tantalum, aluminum, iron, vanadium, chromium, chromium-based alloys and nickel-based alloys, and combinations thereof;

a first layer of a first resistive material having a thickness of between 50 Å and 2 μm formed directly on said oxide layer;

a second layer of a second resistive material having a thickness of between 50 Å and 2 μm formed directly on said first layer of said first resistive material,

wherein said first resistive material has a resistance different from said second resistive material, and at least one of said first layer of said first resistive material and said second layer of said second resistive material includes a material selected from the group consisting of aluminum, zinc, nickel, nickel/chromium, nickel/chromium/aluminum/silicon alloy, titanium, vanadium, chromium, tantalum, iron, manganese and alloys, oxides, nitrides and silicides thereof.